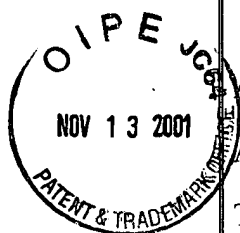


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicant(s): Heung-Kyu Kwon, Min-Kyo Cho  
Assignee: Samsung Electronics Co., Ltd.  
Title: Semiconductor Chip Package And Method Of Fabricating The Same  
Serial No.: 09/464,322 Filing Date: December 15, 1999  
Examiner: C. Chu Group Art Unit: 2815  
Docket No.: AB-881 US

#8  
12-4-01  
T. Flowers

San Jose, California  
November 13, 2001

BOX NON FEE AMENDMENT  
COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

This response is to the September 12, 2001 Office Action which has a statutorily shortened period for response that ends December 12, 2001.

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IN THE CLAIMS

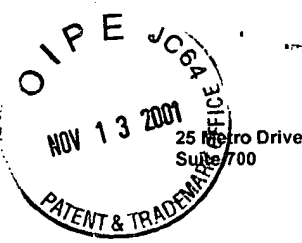
For the Examiner's convenience, a clean version of the entire set of pending claims is provided as follows. No amendments are made.

No changes

1. (Previously Amended) A semiconductor chip package comprising:
  - a substrate having a plurality of bonding pads;
  - a semiconductor chip having a plurality of conductive bumps on a front side thereof, the conductive bumps contacting the bonding pads;
  - a heat slug bonded to a backside of the semiconductor chip; and
  - a solder film that bonds the heat slug to the backside of the semiconductor chip.
2. The semiconductor chip package of claim 1, wherein the solder film includes one selected from a group consisting of Pb, Sn, Ag, In, and Bi.

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Docket No.: AB-881 US

November 13, 2001

Box Non-Fee Amendment  
Commissioner For Patents  
Washington, D.C. 20231

Re: Applicant(s): Heung-Kyu Kwon, Min-Kyo Cho  
Assignee: Samsung Electronics Co., Ltd.  
Title: Semiconductor Chip Package And Method Of Fabricating The Same  
Serial No.: 09/464,322  
Examiner: C. Chu  
Docket No.: AB-881 US  
Filed: December 15, 1999  
Group Art Unit: 2815

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Dear Sir:

Transmitted herewith are the following documents in the above-identified application:

- (1) Return Receipt Postcard;
- (2) This Transmittal Letter (in duplicate);
- (3) Response to Office Action (6 pp).

☒ No additional fee is required.

CLAIMS AS AMENDED

	Claims Remaining <u>After Amendment</u>		Highest No. Previously <u>Paid For</u>		Present <u>Extra</u>		<u>Rate</u>		Additional <u>Fee</u>	
Total Claims	20	Minus	20	=	0	x	\$18.00	\$	0.00	
Independent Claims	3	Minus	3	=	0	x	\$84.00	\$	0.00	
<b><u>Total additional fee for this Amendment:</u></b>								\$	<u>0.00</u>	
<input checked="" type="checkbox"/>	Conditional Petition for Extension of Time: If an extension of time is required for timely filing of the enclosed document(s) after all papers filed with this transmittal have been considered, an extension of time is hereby requested.									
<input checked="" type="checkbox"/>	Please charge our Deposit Account No. 19-2386 in the amount of								\$	<u>0.00</u>
<input checked="" type="checkbox"/>	Also, charge any additional fees required and credit any overpayment to our Deposit Account No. 19-2386.									
<b>Total:</b>								\$	<u>0.00</u>	

Express Mail Label No:  
EL 699 358 764 US  
November 13, 2001

Respectfully submitted,  
*David W. Heid*  
David W. Heid  
Attorney for Applicant(s)  
Reg. No. 25,875